

L Number	Hits	Search Text	DB	Time stamp
1	3	"6646332"	USPAT; EPO; JPO; DERWENT	2004/07/24 21:52
2	2476	semiconductor with package and (vias or holes) and solder and adhesive	USPAT; EPO; JPO; DERWENT	2004/07/24 21:54
3	7	"multi-layer" adj2 semiconductor with package and (vias or holes) and solder and adhesive	USPAT; EPO; JPO; DERWENT	2004/07/24 21:54